

CALL FOR

August 17-20, 2023 Xi'an, Shaanxi, China



2023 IEEE 11th International Conference on Information, Communication and Networks

Track

The 2023 IEEE 11th International Conference on Information, Communication and Networks (ICICN) is set to take place in Xi'an, Shaanxi, China during August 17-20, 2023.



All submissions will be peer reviewed. Accepted, registered and presented papers will be published in the ICICN 2023 IEEE conference Proceedings, included in IEEE Xplore and indexed by **El Compendex, SCOPUS**, etc.

Quantum Information and Related Quantum Technologies

Submission Deadline: June 10, 2023

Brief introduction

Quantum information processing, using a quantum platform as the information carrier and processor, may be able to transmit data that is fundamentally secure, as well as solve problems beyond the power of modern conventional computers. So far, many outstanding experimental teams have done numerous pioneering works with different fashions, such as atomic systems, optical nonlinear crystals, semiconductors, superconducting circuits, trapped ions, and NV color centers, etc. This tract offers engineers and scientists in universities, research centers and industry to present their work and to share experiences and ideas. It will focus on discussing the quantum information and technology.

Topics Interested topics include (but not limited to):

- Quantum communication

- Quantum computation

Fundamental quantum theory

- Quantum metrology
- Related quantum technologies (Atoms, Optics, Solids, etc.)

Track Chairs and Co-chairs:

Pei Zhang, Xi'an Jiaotong University, China Yin Cai, Xi'an Jiaotong University, China Feng Li, Xi'an Jiaotong University, China

Track TPC Members

Peng Xue, Beijing Computational Science Research Center, China

Jin Liu, Sun Yat-Sen University, China

Lijian Zhang, Nanjing University, China

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